

ABSTRACT

The present disclosure provides a material path establishment method, a material scheduling method, and semiconductor process equipment. The material path establishment method includes: obtaining a process path formed by a plurality of chambers through which a material sequentially passes during a process; determining whether there are parallel process chambers; and in response to existence of parallel process chambers, splitting the process path into a base path and N backup paths. The parallel process chambers included in the base path and the N backup paths are different, the transfer chamber connected to the parallel process chambers in the base path is a first transfer chamber, the first transfer chamber is the transfer chamber directly connected to a load/unload chamber, and the transfer chamber connected to the parallel process chambers in the i-th backup path is an (i+1)-th transfer chamber arranged after the first transfer chamber. The solution can be compatible with parallel process chambers executing the same process, thereby improving production capacity.